TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150821001
Qualification of FFAB as an additional Wafer Fab site option for select devices in the BICMOS13 process
Change Notification / Sample Request

Date: 8/24/2015
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20150821001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DS100BR210SQE/NOPB	null
DS100KR800SQE/NOPB	null
DS125BR401SQE/NOPB	null
DS125BR820NJYT	null
DS125DF111SQE	null
DS80PCI402SQE/NOPB	null
DS80PCI800SQE/NOPB	null
DS80PCI810NJYT	null
LMX2581SQE/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150821001	**PCN Date:**	08/24/2015
Title:	Qualification of FFAB as an additional Wafer Fab site option for select devices in BICMOS13 Technology		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	11/24/2015	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of FFAB as an additional Wafer Fab site option for the products listed in the product affected section of this document.

Current Wafer Fab Site	Process	Wafer Diameter
MAINEFAB	BICMOS13	200mm

Additional Wafer Fab Site	Process	Wafer Diameter
FFAB	BICMOS13	200mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland

New

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO :USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

DS100BR210SQ/NOPB	DS110DX410SQ/NOPB	DS125BR820NJYR	DS80PCI800SQ/NOPB
DS100BR210SQE/NOPB	DS110DX410SQE/NOPB	DS125BR820NJYT	DS80PCI800SQE/NOPB
DS100DX410SQ/NOPB	DS125BR210SQ/NOPB	DS125DF111SQ	DS80PCI810NJYR
DS100DX410SQE/NOPB	DS125BR210SQE/NOPB	DS125DF111SQE	DS80PCI810NJYT
DS100KR401SQ/NOPB	DS125BR401SQ/NOPB	DS125DF410SQ/NOPB	LM97937RMER
DS100KR401SQE/NOPB	DS125BR401SQE/NOPB	DS125DF410SQE/NOPB	LM97937RMET
DS100KR800SQ/NOPB	DS125BR800SQ/NOPB	DS125RT410SQ/NOPB	LMX2581SQ/NOPB
DS100KR800SQE/NOPB	DS125BR800SQE/NOPB	DS125RT410SQE/NOPB	LMX2581SQE/NOPB
DS110DF111SQ/NOPB	DS125BR810NJYR	DS80PCI402SQ/NOPB	LMX2581SQX/NOPB
DS110DF111SQE/NOPB	DS125BR810NJYT	DS80PCI402SQE/NOPB	

Qualification Report

BiCMOS13 Process (LMX2581B) Release at FFAB

Approve Date 31-Jul-2015

Product Attributes

Die Attributes	Qual Device: LMX2581SQENOPB
Wafer Fab Supplier	FFAB
Wafer Fab Process	BC13
Wafer Diameter	200mm

- QBS: Qual by Similarity
- Qual Device LMX2581SQENOPB is qualified at LEVEL3-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMX2581SQENOPB
ELFR	Early Life Failure Rate, Tj=160C	48 Hours	3/2400/0
HTOL	Life Test, Tj=160C	500 Hours	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
TC	Temperature Cycle, -40/125C	1000 Cycles	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
HBM	ESD - HBM	2000 V	3/9/0
CDM	ESD - CDM	750 V	3/9/0
LU	Latch-up	(per JESD78)	3/18/0
ED	Electrical Characterization	Per datasheet parameters	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com